



TM04P03I

P-Channel Enhancement Mosfet

General Description

- Low $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

Applications

- Load switch
- PWM

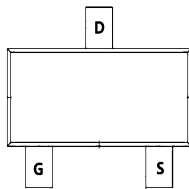
General Features

$V_{DS} = -30V$ $I_D = -4A$
 $R_{DS(ON)} = 48m\Omega$ (typ) @ $V_{GS} = -10V$

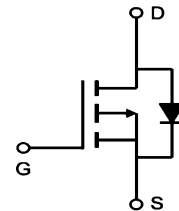
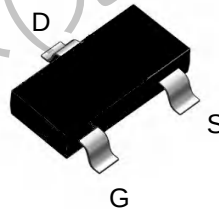
100% UIS Tested
100% R_g Tested



I: SOT-23



Marking: A19T



Absolute Maximum Ratings $T_A = 25^\circ C$ un (less otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V$	-4.0	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V$	-2.4	A
I_{DM}	Pulsed Drain Current ²	-16	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ³	1.2	W
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 175	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	162	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	---	$^\circ C/W$



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Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = -250μA, V _{GS} = 0V	-30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -30V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±12V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-0.6	-0.9	-1.3	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = -10V, I _D = -4A	-	48	62	mΩ
		V _{GS} = -4.5V, I _D = -3A	-	56	73	mΩ
		V _{GS} = -2.5V, I _D = -3A	-	---	---	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = -15V, f = 1MHz	-	553	-	pF
C _{oss}	Output Capacitance		-	57	-	pF
C _{rss}	Reverse Transfer Capacitance		-	35	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to -4.5V V _{DS} = -15V, I _D = -3A	-	6.5	-	nC
Q _{gs}	Gate Source Charge		-	1.4	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	1.7	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = -4.5V, V _{DD} = -15V I _D = -3A, R _{GEN} = 3Ω	-	10	-	ns
t _r	Turn-On Rise Time		-	86	-	ns
t _{d(off)}	Turn-Off DelayTime		-	150	-	ns
t _f	Turn-Off Fall Time		-	357	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-4	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-16	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -4A	-	-	-1.2	V
trr	Body Diode Reverse Recovery Time	I _F = -3A, di/dt = 80A/us	-	36	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	5	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Typical Performance Characteristics

Figure 1: Output Characteristics

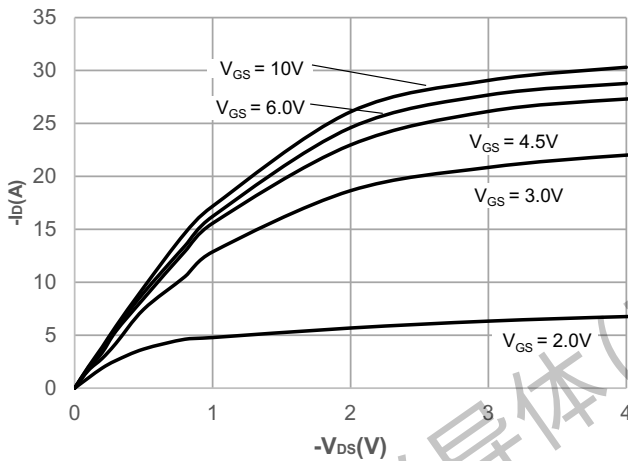


Figure 2: Typical Transfer Characteristics

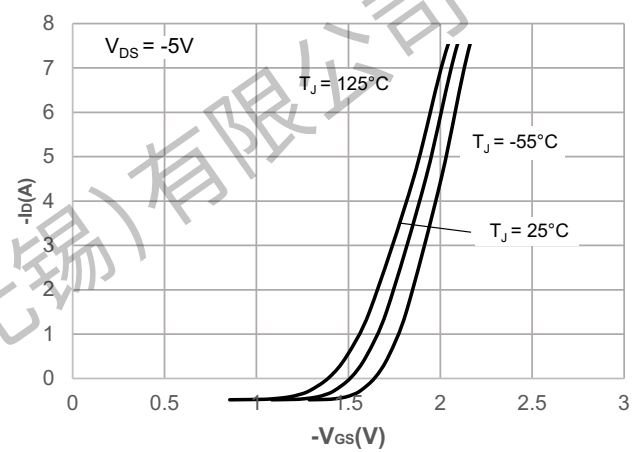


Figure 3: On-resistance vs. Drain Current

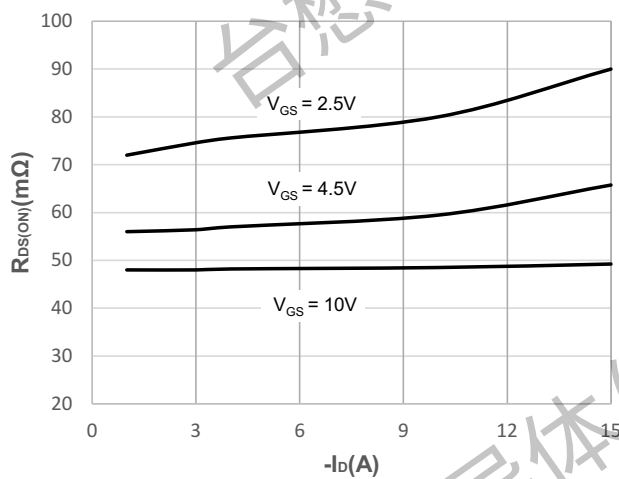


Figure 4: Body Diode Characteristics

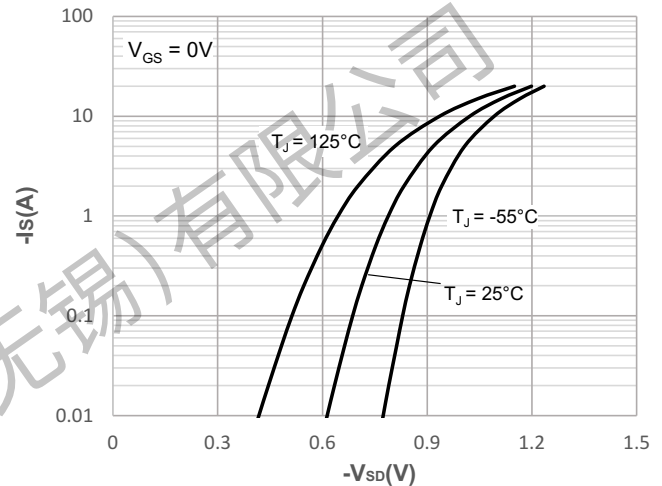


Figure 5: Gate Charge Characteristics

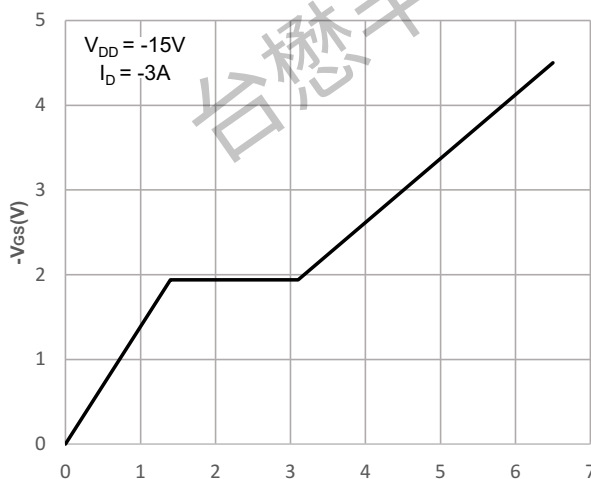
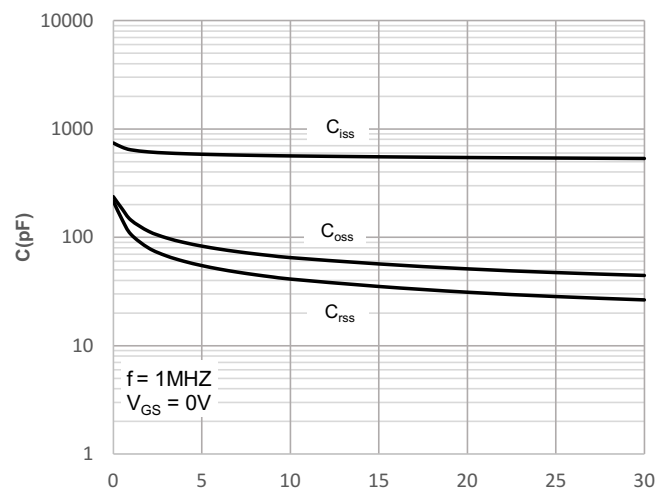


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

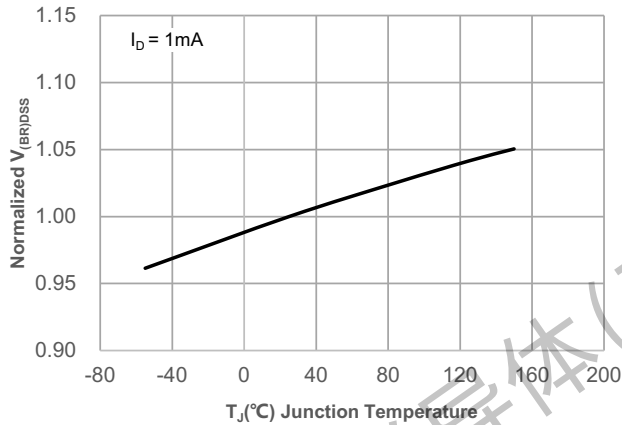


Figure 8: Normalized on Resistance vs. Junction Temperature

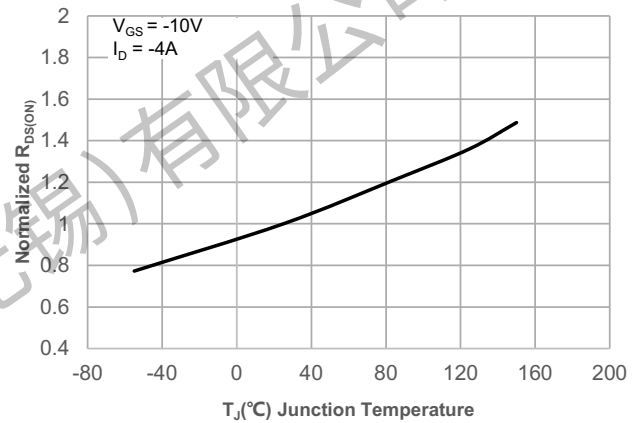


Figure 9: Maximum Safe Operating Area

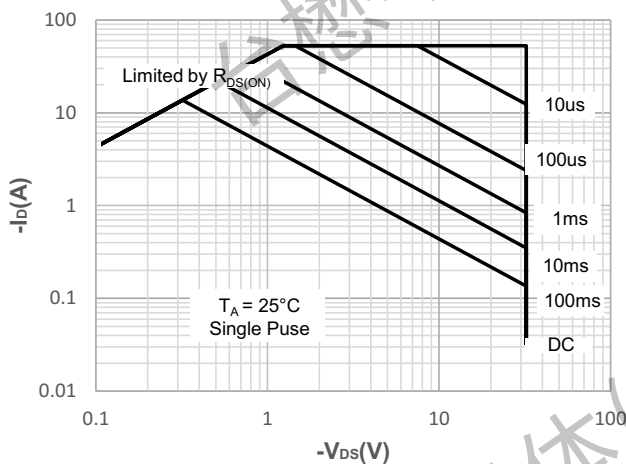


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

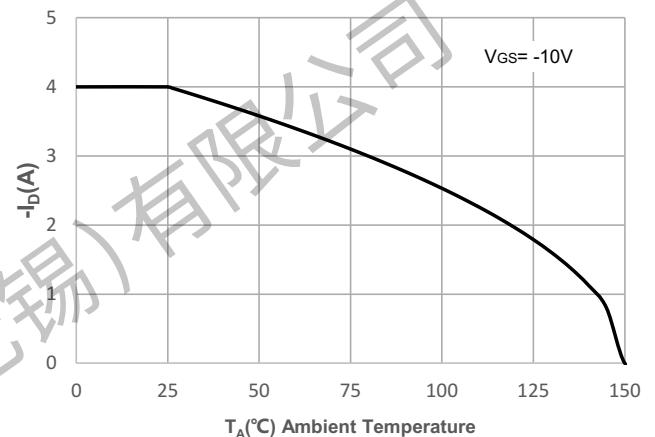


Figure 11: Normalized Maximum Transient Thermal Impedance

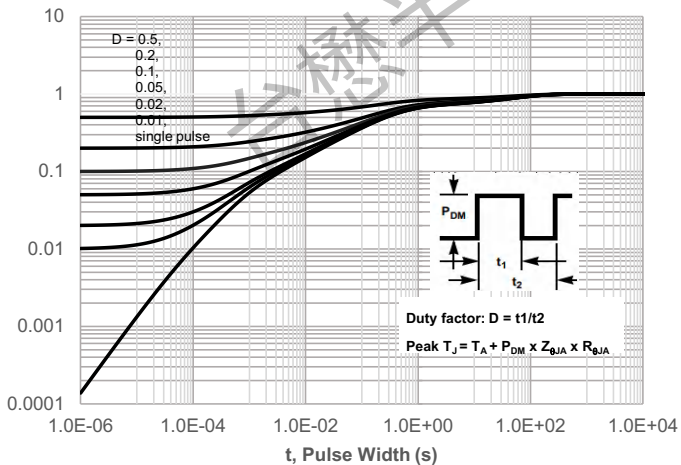
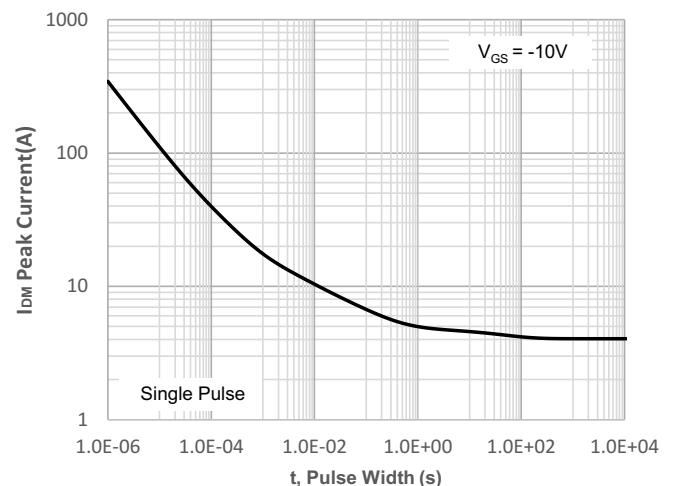


Figure 12: Peak Current Capacity

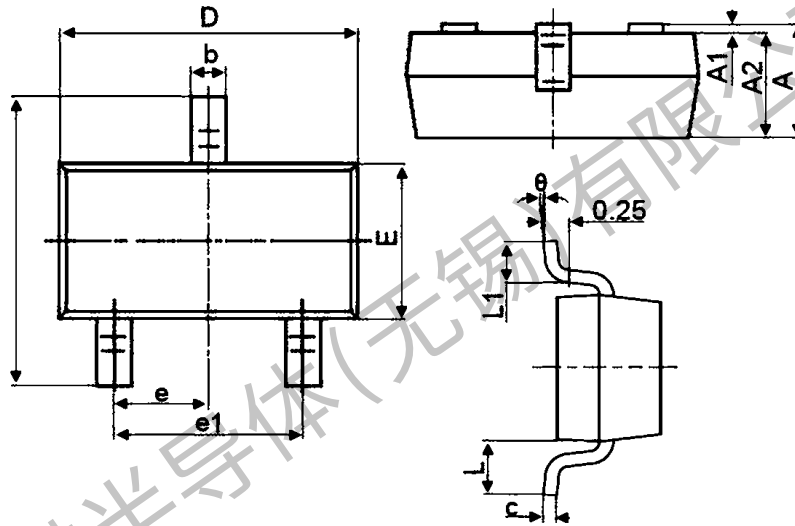




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Package Mechanical Data:SOT-23



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

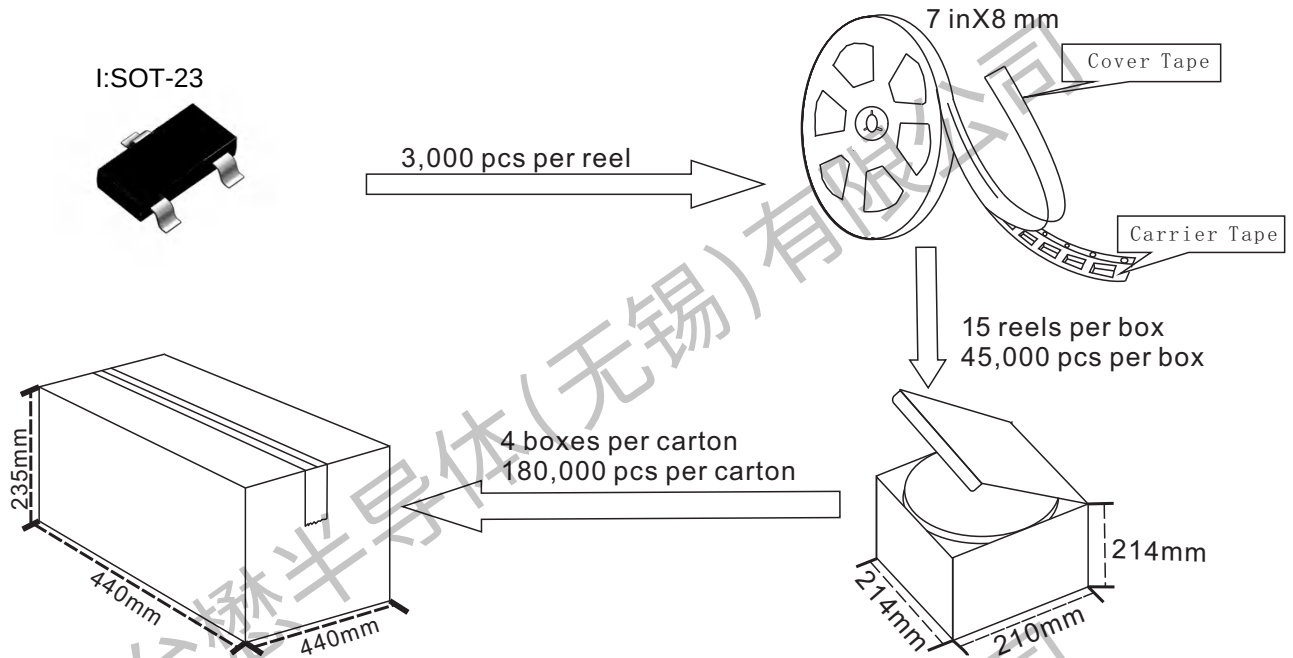


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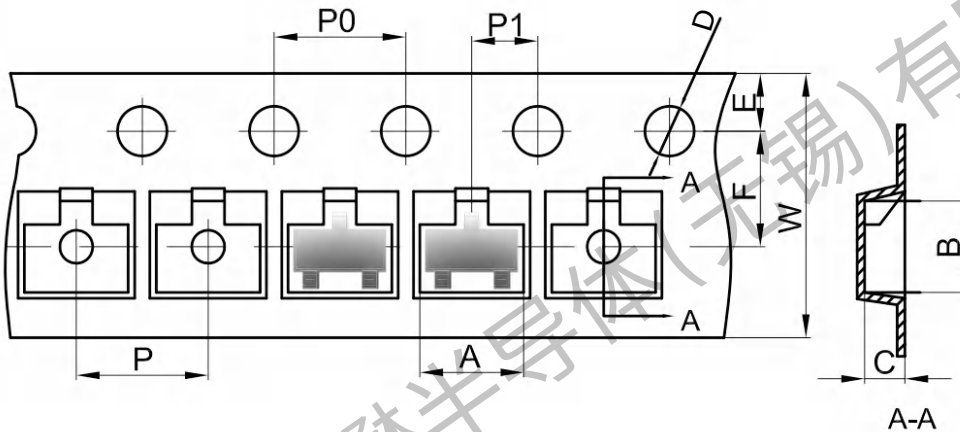
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SOT-23 Packing

1. The method of packaging and dimension are shown as below figure. (Dimension in mm)



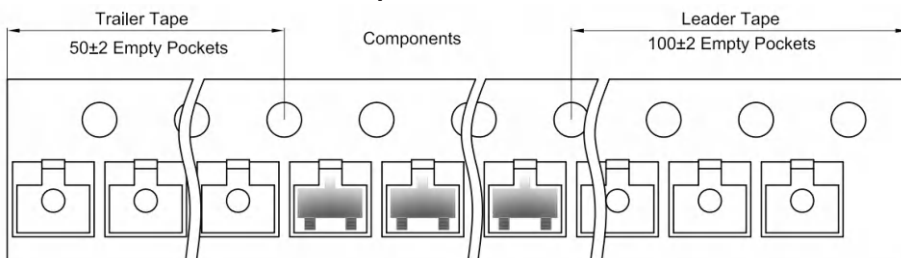
SOT-23 Embossed Carrier Tape



Dimensions are in millimeter

Pkg type	A	B	C	D	E	F	P0	P	P1	W
SOT-23	3.15	2.77	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

SOT-23 Tape Leader and Trailer



Important Notices and Disclaimers

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Revision history:

Date	Rev	Description	Page
2023.05.19	24.05	Original	